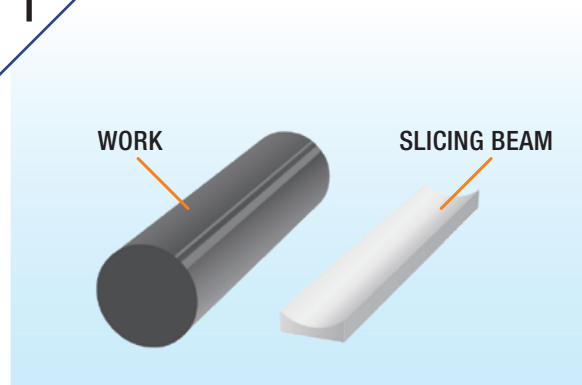
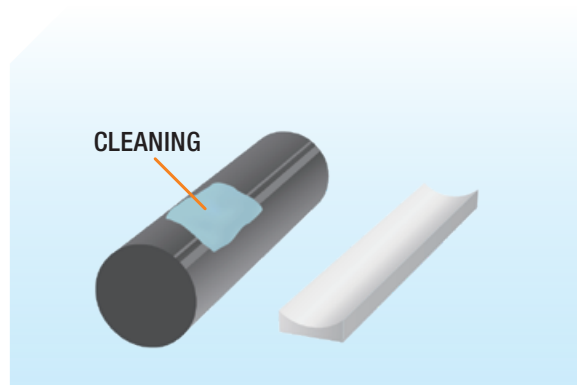


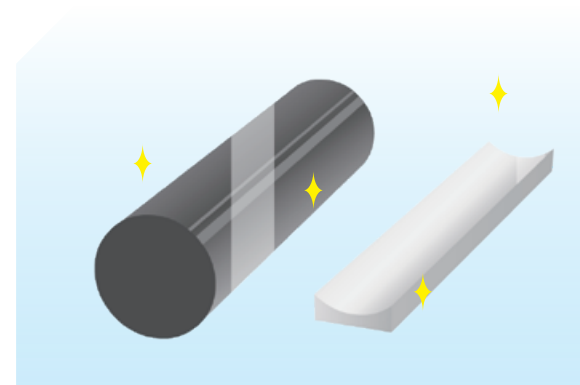
1 清洗



准备晶棒与加工底座

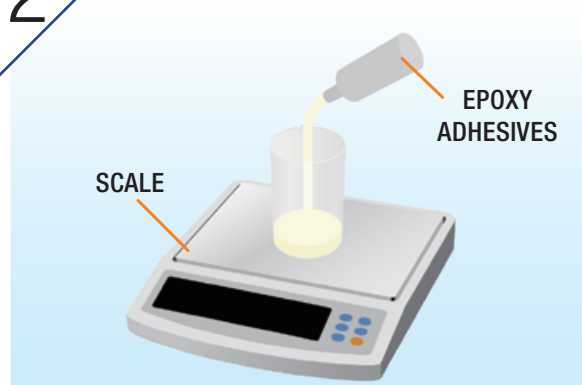


清洗涂胶面

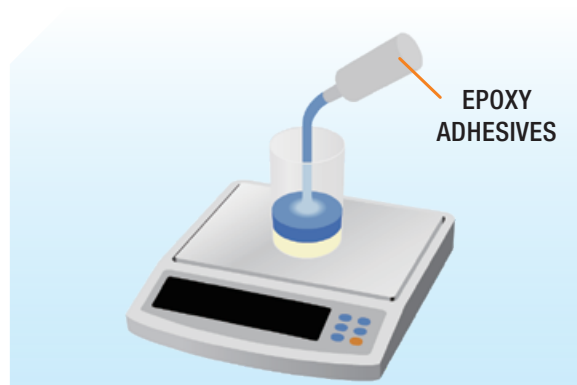


清洗结束

2 称重



测定重量并准备相应的环氧树脂胶



正确配比主剂与硬化剂的混合量

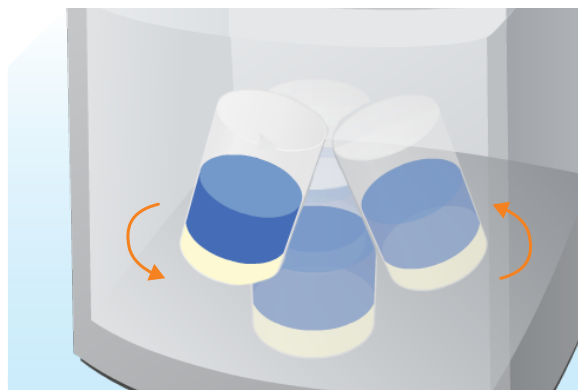


称重完成

3 混合



推荐以机械而非人力的方式进行搅拌

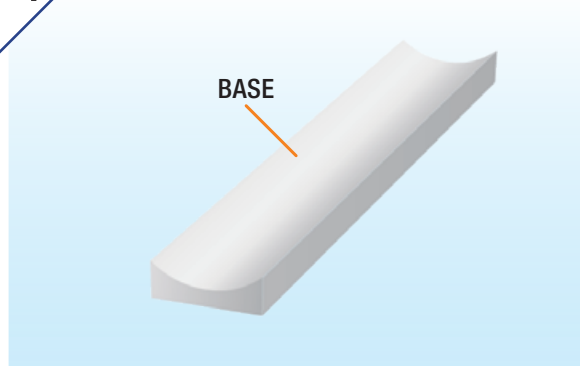


利用离心力将两种液体进行搅拌

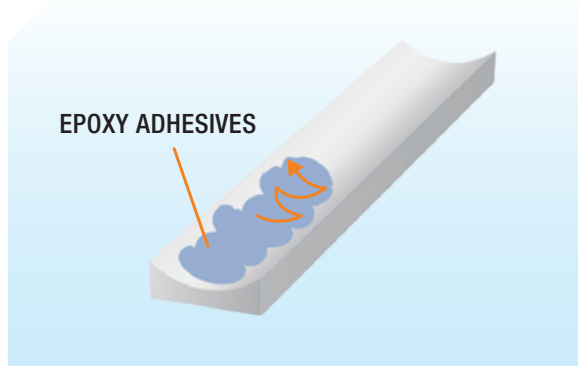


充分搅拌后形成环氧树脂胶

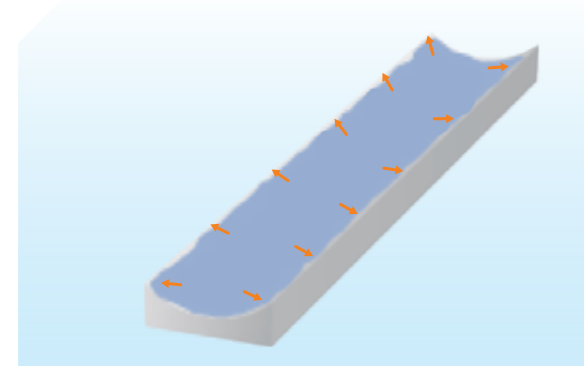
4 涂胶



准备加工底座

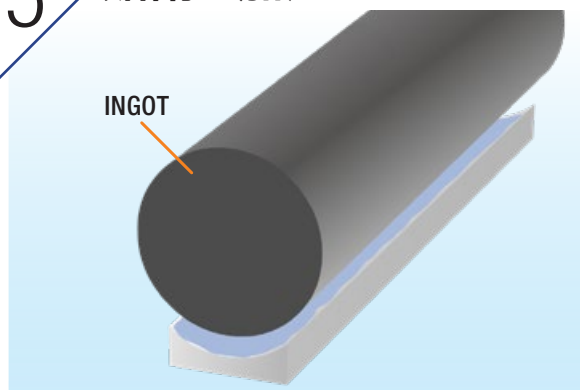


快速地涂抹环氧树脂胶

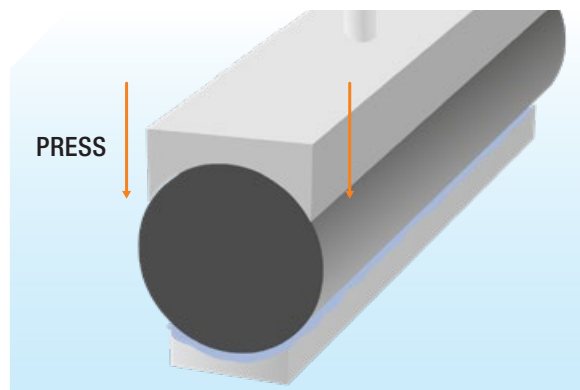


接着面要充分均匀涂抹

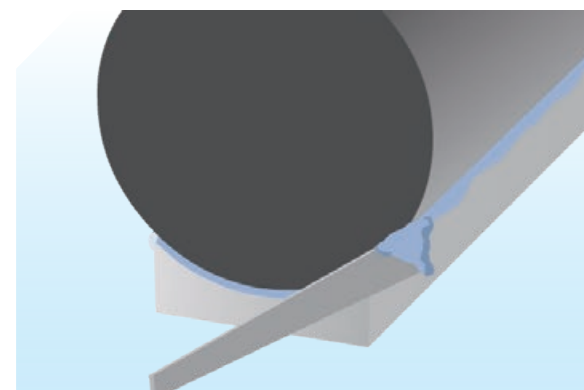
5 贴附&加压



请在可操作时间内完成晶棒的贴附作业

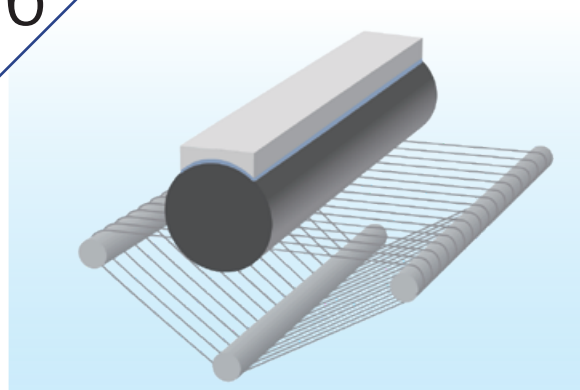


通过外力使晶棒和加工底座接着均匀

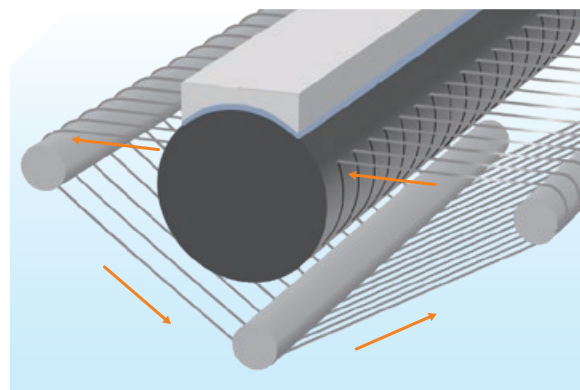


擦拭晶棒与加工底座之间溢出的环氧树脂胶

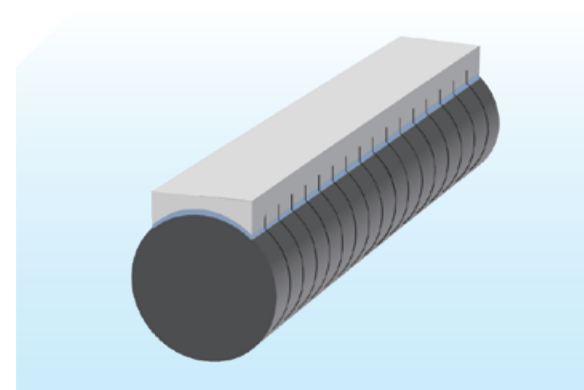
6 切片



金刚线与工件位置设定

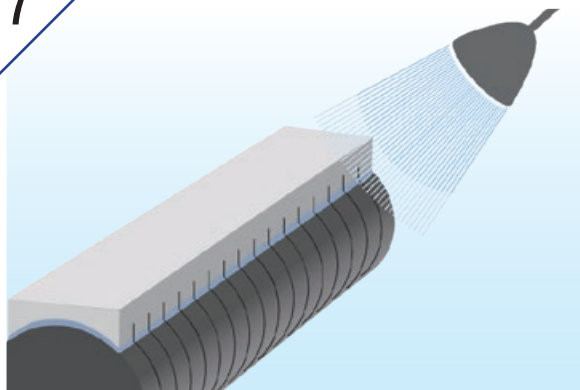


切片加工中



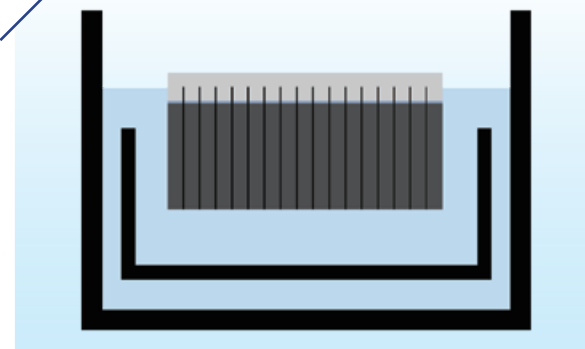
切片加工完成

7 清洗

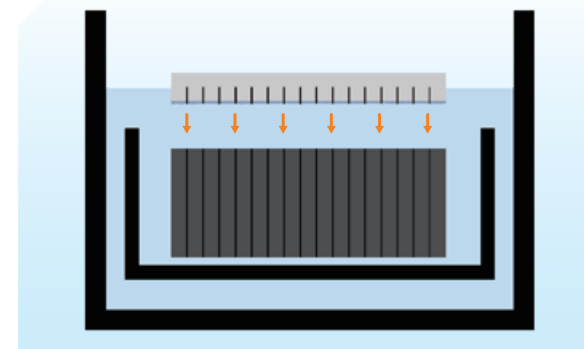


洗去切削液

8-1 分离

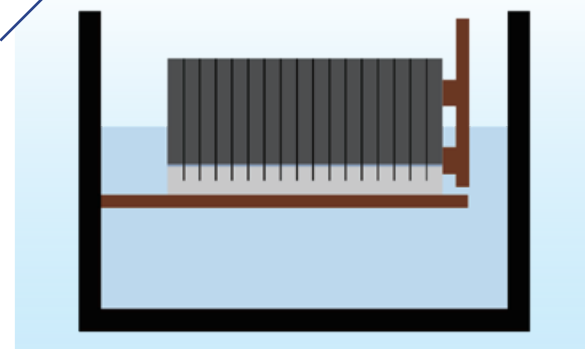


将工件浸入剥离槽内

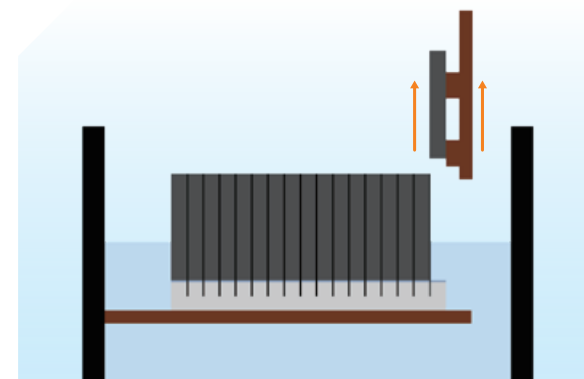


将晶圆从环氧树脂胶上剥离

8-2 分离 by EQUIPMENT

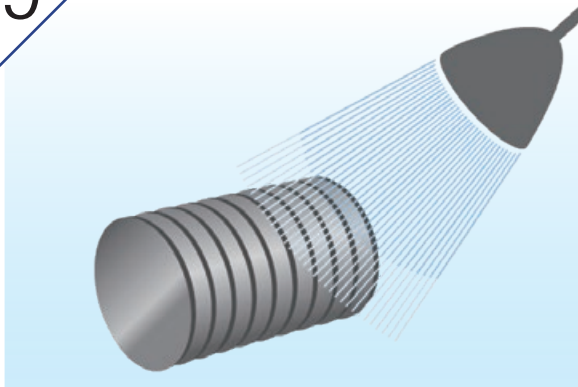


将工件安置于分离设备上

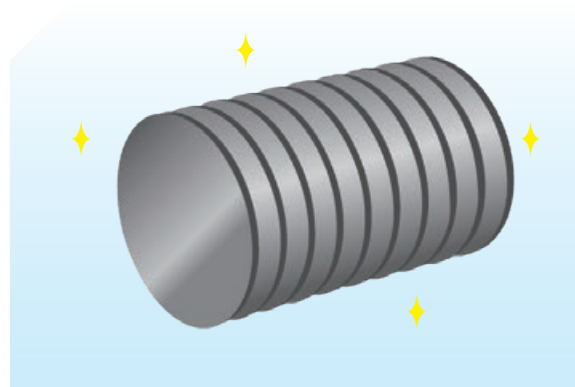


分离设备会把晶圆分开

9 清洗



对晶圆进行清洗



切片工序完成